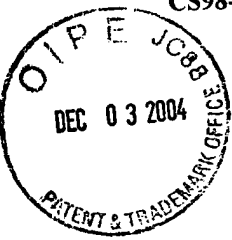


AF/ 2813
Hw/A

October 22, 2004



TO: Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

FROM: George O. Saile, Reg. No. 19,572
28 Davis Ave.
Poughkeepsie, N.Y. 12603

SUBJECT: Serial #: 09/817,473
File Date: 03/26/2001
Inventor: YI, XU ET AL.
Examiner: NGUYEN, THANH T.
Art Unit: 2813
Title: GAP FILLING PROCESS IN INTEGRATED
CIRCUITS USING LOW DIELECTRIC CONSTANT
MATERIALS

RESPONSE TO OFFICE ACTION

This is in response to the Office Action dated October 01, 2004. Please consider the following in regards to the above referenced application.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on December 1, 2004.

Signature

Date:

12/1/04

Stephen B. Ackerman, Reg. No. 37,761

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Listing of Claims: